ABSTRACT

A multi-chip integrated module includes a transparent substrate, at least two chips, and a circuit substrate. In this case, a circuit layer is formed on one surface of the transparent substrate, wherein the circuit layer formed on the surface of the transparent substrate includes a circuit for electrical inter-connection and a plurality of electrical pads for electrical external-connection. The chips are mounted on the transparent substrate by way of a flip-chip bonding, respectively. Thus, the chips and the circuit for electrical inter-connection construct a circuit system. The circuit substrate attaches to the transparent substrate, on which the chips are mounted. The circuit substrate at least includes a circuit layer, which electrically connects to the electrical pads of the transparent substrate. Furthermore, an additional multi-chip integrated module is also disclosed.